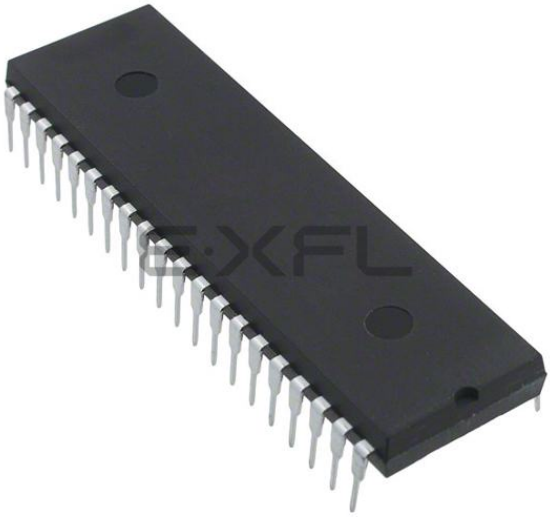

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c44-33e-p

NOTES:

TABLE 4-4: INITIALIZATION CONDITIONS FOR SPECIAL FUNCTION REGISTERS

Register	Address	Power-on Reset	$\overline{\text{MCLR}}$ Reset WDT Reset	Wake-up from SLEEP through interrupt
Unbanked				
INDF0	00h	0000 0000	0000 0000	0000 0000
FSR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h	0000h	0000h	PC + 1(2)
PCLATH	03h	0000 0000	0000 0000	uuuu uuuu
ALUSTA	04h	1111 xxxx	1111 uuuu	1111 uuuu
T0STA	05h	0000 000-	0000 000-	0000 000-
CPUSTA(3)	06h	--11 11--	--11 qq--	--uu qq--
INTSTA	07h	0000 0000	0000 0000	uuuu uuuu(1)
INDF1	08h	0000 0000	0000 0000	uuuu uuuu
FSR1	09h	xxxx xxxx	uuuu uuuu	uuuu uuuu
WREG	0Ah	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR0L	0Bh	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR0H	0Ch	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLPTRL (4)	0Dh	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLPTRH (4)	0Eh	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLPTRL (5)	0Dh	0000 0000	0000 0000	uuuu uuuu
TBLPTRH (5)	0Eh	0000 0000	0000 0000	uuuu uuuu
BSR	0Fh	0000 0000	0000 0000	uuuu uuuu
Bank 0				
PORTA	10h	0-xx xxxx	0-uu uuuu	uuuu uuuu
DDRB	11h	1111 1111	1111 1111	uuuu uuuu
PORTB	12h	xxxx xxxx	uuuu uuuu	uuuu uuuu
RCSTA	13h	0000 -00x	0000 -00u	uuuu -uuu
RCREG	14h	xxxx xxxx	uuuu uuuu	uuuu uuuu
TXSTA	15h	0000 --1x	0000 --1u	uuuu --uu
TXREG	16h	xxxx xxxx	uuuu uuuu	uuuu uuuu
SPBRG	17h	xxxx xxxx	uuuu uuuu	uuuu uuuu
Bank 1				
DDRC	10h	1111 1111	1111 1111	uuuu uuuu
PORTC	11h	xxxx xxxx	uuuu uuuu	uuuu uuuu
DDRD	12h	1111 1111	1111 1111	uuuu uuuu
PORTD	13h	xxxx xxxx	uuuu uuuu	uuuu uuuu
DDRE	14h	---- -111	---- -111	---- -uuu
PORTE	15h	---- -xxx	---- -uuu	---- -uuu
PIR	16h	0000 0010	0000 0010	uuuu uuuu(1)
PIE	17h	0000 0000	0000 0000	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented read as '0', q = value depends on condition.

Note 1: One or more bits in INTSTA, PIR will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GLINTD bit is cleared, the PC is loaded with the interrupt vector.

3: See Table 4-3 for reset value of specific condition.

4: Only applies to the PIC17C42.

5: Does not apply to the PIC17C42.

6.2.2.2 CPU STATUS REGISTER (CPUSTA)

The CPUSTA register contains the status and control bits for the CPU. This register is used to globally enable/disable interrupts. If only a specific interrupt is desired to be enabled/disabled, please refer to the INTerrupt STAtus (INTSTA) register and the Peripheral Interrupt Enable (PIE) register. This register also indicates if the stack is available and contains the Power-down ($\overline{PD}$) and Time-out ($\overline{TO}$) bits. The $\overline{TO}$, $\overline{PD}$, and STKAV bits are not writable. These bits are set and cleared according to device logic. Therefore, the result of an instruction with the CPUSTA register as destination may be different than intended.

FIGURE 6-8: CPUSTA REGISTER (ADDRESS: 06h, UNBANKED)

U - 0	U - 0	R - 1	R/W - 1	R - 1	R - 1	U - 0	U - 0
—	—	STKAV	GLINTD	$\overline{TO}$	$\overline{PD}$	—	—
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, Read as '0'
- n = Value at POR reset

bit 7-6: **Unimplemented**: Read as '0'

bit 5: **STKAV**: Stack Available bit
This bit indicates that the 4-bit stack pointer value is Fh, or has rolled over from Fh→ 0h (stack overflow).
1 = Stack is available
0 = Stack is full, or a stack overflow may have occurred (Once this bit has been cleared by a stack overflow, only a device reset will set this bit)

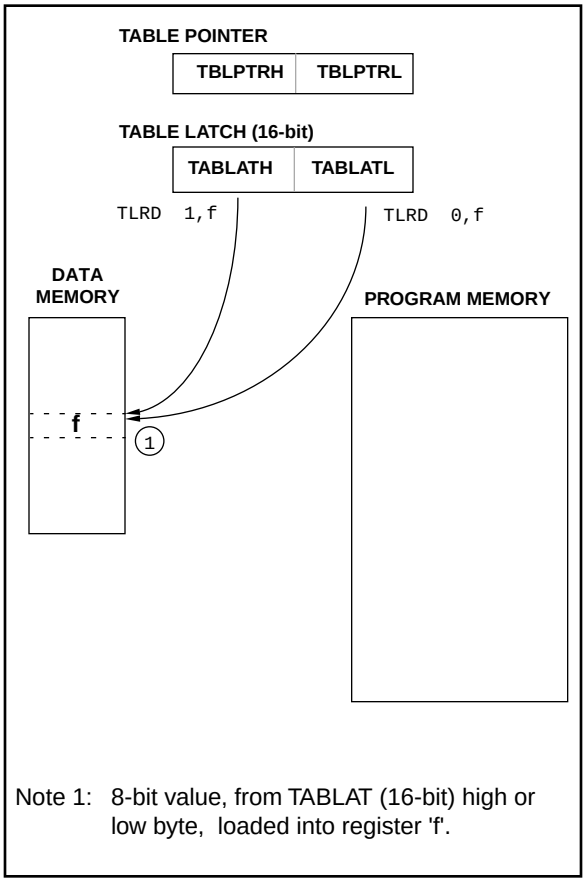
bit 4: **GLINTD**: Global Interrupt Disable bit
This bit disables all interrupts. When enabling interrupts, only the sources with their enable bits set can cause an interrupt.
1 = Disable all interrupts
0 = Enables all un-masked interrupts

bit 3: **$\overline{TO}$**: WDT Time-out Status bit
1 = After power-up or by a CLRWDT instruction
0 = A Watchdog Timer time-out occurred

bit 2: **$\overline{PD}$**: Power-down Status bit
1 = After power-up or by the CLRWDT instruction
0 = By execution of the SLEEP instruction

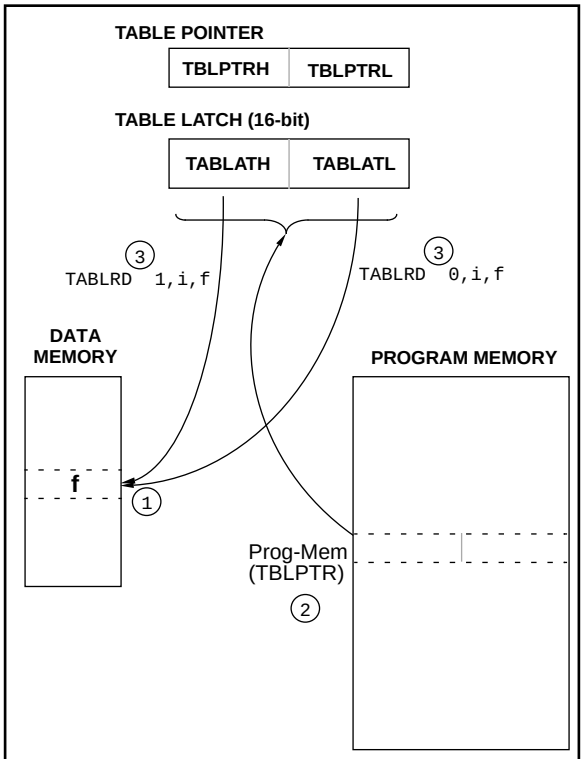
bit 1-0: **Unimplemented**: Read as '0'

FIGURE 7-3: TLRD INSTRUCTION OPERATION



Note 1: 8-bit value, from TABLAT (16-bit) high or low byte, loaded into register 'f'.

FIGURE 7-4: TABLRD INSTRUCTION OPERATION



Note 1: 8-bit value, from TABLAT (16-bit) high or low byte, loaded into register 'f'.
2: 16-bit value at Program Memory (TBLPTR) loaded into TABLAT register.
3: If "i" = 1, then TBLPTR = TBLPTR + 1, If "i" = 0, then TBLPTR is unchanged.

Example 8-3 shows the sequence to do a 16 x 16 unsigned multiply. Equation 8-1 shows the algorithm that is used. The 32-bit result is stored in 4 registers RES3:RES0.

EQUATION 8-1: 16 x 16 UNSIGNED MULTIPLICATION ALGORITHM

$$
\begin{aligned}
RES3:RES0 &= ARG1H:ARG1L * ARG2H:ARG2L \\
&= (ARG1H * ARG2H * 2^{16}) + \\
&\quad (ARG1H * ARG2L * 2^{8}) + \\
&\quad (ARG1L * ARG2H * 2^{8}) + \\
&\quad (ARG1L * ARG2L)
\end{aligned}
$$

EXAMPLE 8-3: 16 x 16 MULTIPLY ROUTINE

```
   MOVFP    ARG1L, WREG
   MULWF    ARG2L       ; ARG1L * ARG2L ->
                        ;   PRODH:PRODL
   MOVPF    PRODH, RES1 ;
   MOVPF    PRODL, RES0 ;
;
   MOVFP    ARG1H, WREG
   MULWF    ARG2H       ; ARG1H * ARG2H ->
                        ;   PRODH:PRODL
   MOVPF    PRODH, RES3 ;
   MOVPF    PRODL, RES2 ;
;
   MOVFP    ARG1L, WREG
   MULWF    ARG2H       ; ARG1L * ARG2H ->
                        ;   PRODH:PRODL
   MOVFP    PRODL, WREG ;
   ADDWF    RES1, F     ; Add cross
   MOVFP    PRODH, WREG ;    products
   ADDWFC   RES2, F     ;
   CLRF     WREG, F     ;
   ADDWFC   RES3, F     ;
;
   MOVFP    ARG1H, WREG ;
   MULWF    ARG2L       ; ARG1H * ARG2L ->
                        ;   PRODH:PRODL

   MOVFP    PRODL, WREG ;
   ADDWF    RES1, F     ; Add cross
   MOVFP    PRODH, WREG ;    products
   ADDWFC   RES2, F     ;
   CLRF     WREG, F     ;
   ADDWFC   RES3, F     ;
```

TABLE 9-7: PORTD FUNCTIONS

Name	Bit	Buffer Type	Function
RD0/AD8	bit0	TTL	Input/Output or system bus address/data pin.
RD1/AD9	bit1	TTL	Input/Output or system bus address/data pin.
RD2/AD10	bit2	TTL	Input/Output or system bus address/data pin.
RD3/AD11	bit3	TTL	Input/Output or system bus address/data pin.
RD4/AD12	bit4	TTL	Input/Output or system bus address/data pin.
RD5/AD13	bit5	TTL	Input/Output or system bus address/data pin.
RD6/AD14	bit6	TTL	Input/Output or system bus address/data pin.
RD7/AD15	bit7	TTL	Input/Output or system bus address/data pin.

Legend: TTL = TTL input.

TABLE 9-8: REGISTERS/BITS ASSOCIATED WITH PORTD

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
13h, Bank 1	PORTD	RD7/ AD15	RD6/ AD14	RD5/ AD13	RD4/ AD12	RD3/ AD11	RD2/ AD10	RD1/ AD9	RD0/ AD8	xxxx xxxx	uuuu uuuu
12h, Bank 1	DDRD	Data direction register for PORTD								1111 1111	1111 1111

Legend: x = unknown, u = unchanged.

Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and the Watchdog Timer Reset.

12.0 TIMER1, TIMER2, TIMER3, PWMS AND CAPTURES

The PIC17C4X has a wealth of timers and time-based functions to ease the implementation of control applications. These time-base functions include two PWM outputs and two Capture inputs.

Timer1 and Timer2 are two 8-bit incrementing timers, each with a period register (PR1 and PR2 respectively) and separate overflow interrupt flags. Timer1 and Timer2 can operate either as timers (increment on internal Fosc/4 clock) or as counters (increment on falling edge of external clock on pin RB4/TCLK12). They are also software configurable to operate as a single 16-bit timer. These timers are also used as the time-base for the PWM (pulse width modulation) module.

Timer3 is a 16-bit timer/counter consisting of the TMR3H and TMR3L registers. This timer has four other associated registers. Two registers are used as a 16-bit period register or a 16-bit Capture1 register (PR3H/CA1H:PR3L/CA1L). The other two registers are strictly the Capture2 registers (CA2H:CA2L). Timer3 is the time-base for the two 16-bit captures.

TMR3 can be software configured to increment from the internal system clock or from an external signal on the RB5/TCLK3 pin.

Figure 12-1 and Figure 12-2 are the control registers for the operation of Timer1, Timer2, and Timer3, as well as PWM1, PWM2, Capture1, and Capture2.

FIGURE 12-1: TCON1 REGISTER (ADDRESS: 16h, BANK 3)

R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0
CA2ED1	CA2ED0	CA1ED1	CA1ED0	T16	TMR3CS	TMR2CS	TMR1CS
bit7							bit0

R = Readable bit
W = Writable bit
-n = Value at POR reset

bit 7-6: **CA2ED1:CA2ED0**: Capture2 Mode Select bits
00 = Capture on every falling edge
01 = Capture on every rising edge
10 = Capture on every 4th rising edge
11 = Capture on every 16th rising edge

bit 5-4: **CA1ED1:CA1ED0**: Capture1 Mode Select bits
00 = Capture on every falling edge
01 = Capture on every rising edge
10 = Capture on every 4th rising edge
11 = Capture on every 16th rising edge

bit 3: **T16**: Timer1:Timer2 Mode Select bit
1 = Timer1 and Timer2 form a 16-bit timer
0 = Timer1 and Timer2 are two 8-bit timers

bit 2: **TMR3CS**: Timer3 Clock Source Select bit
1 = TMR3 increments off the falling edge of the RB5/TCLK3 pin
0 = TMR3 increments off the internal clock

bit 1: **TMR2CS**: Timer2 Clock Source Select bit
1 = TMR2 increments off the falling edge of the RB4/TCLK12 pin
0 = TMR2 increments off the internal clock

bit 0: **TMR1CS**: Timer1 Clock Source Select bit
1 = TMR1 increments off the falling edge of the RB4/TCLK12 pin
0 = TMR1 increments off the internal clock

13.3.2 USART SYNCHRONOUS MASTER RECEPTION

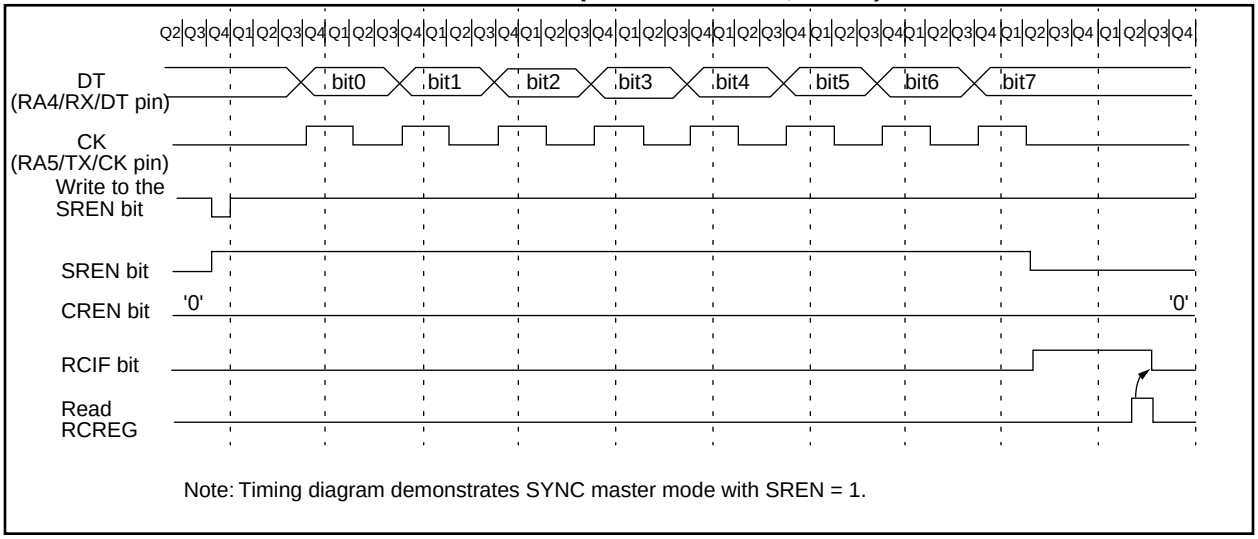
Once synchronous mode is selected, reception is enabled by setting either the SREN (RCSTA<5>) bit or the CREN (RCSTA<4>) bit. Data is sampled on the RA4/RX/DT pin on the falling edge of the clock. If SREN is set, then only a single word is received. If CREN is set, the reception is continuous until CREN is reset. If both bits are set, then CREN takes precedence. After clocking the last bit, the received data in the Receive Shift Register (RSR) is transferred to RCREG (if it is empty). If the transfer is complete, the interrupt bit RCIF (PIR<0>) is set. The actual interrupt can be enabled/disabled by setting/clearing the RCIE (PIE<0>) bit. RCIF is a read only bit which is RESET by the hardware. In this case it is reset when RCREG has been read and is empty. RCREG is a double buffered register; i.e., it is a two deep FIFO. It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte to begin shifting into the RSR. On the clocking of the last bit of the third byte, if RCREG is still full, then the overrun error bit OERR (RCSTA<1>) is set. The word in the RSR will be lost. RCREG can be read twice to retrieve the two bytes in the FIFO. The OERR bit has to be cleared in software. This is done by clearing the CREN bit. If OERR bit is set, transfers from RSR to RCREG are inhibited, so it is essential to clear OERR bit if it is set. The 9th receive bit is buffered the same way as the receive data. Reading the RCREG register will allow the RX9D and FERR bits to be loaded with values for the next received data; therefore, it is essential for the user to read the RCSTA register before reading RCREG in order not to lose the old FERR and RX9D information.

Steps to follow when setting up a Synchronous Master Reception:

1. Initialize the SPBRG register for the appropriate baud rate. See Section 13.1 for details.
2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
3. If interrupts are desired, then set the RCIE bit.
4. If 9-bit reception is desired, then set the RX9 bit.
5. If a single reception is required, set bit SREN. For continuous reception set bit CREN.
6. The RCIF bit will be set when reception is complete and an interrupt will be generated if the RCIE bit was set.
7. Read RCSTA to get the ninth bit (if enabled) and determine if any error occurred during reception.
8. Read the 8-bit received data by reading RCREG.
9. If any error occurred, clear the error by clearing CREN.

Note:	To terminate a reception, either clear the SREN and CREN bits, or the SPEN bit. This will reset the receive logic, so that it will be in the proper state when receive is re-enabled.

FIGURE 13-11: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates SYNC master mode with SREN = 1.

14.2.4 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with series resonance, or one with parallel resonance.

Figure 14-5 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometer biases the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 14-5: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

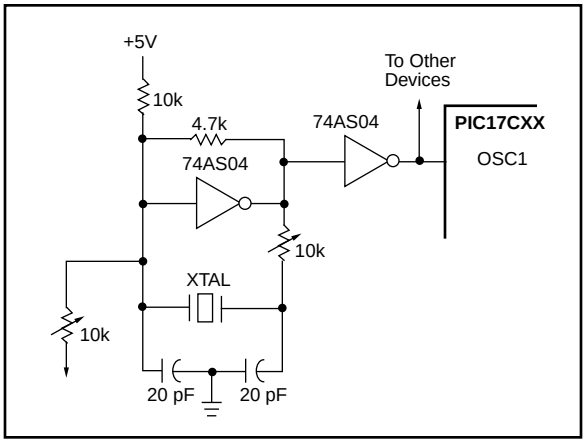
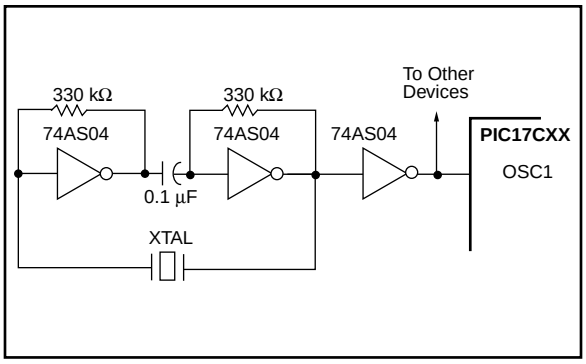


Figure 14-6 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 14-6: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



14.2.5 RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 14-6 shows how the R/C combination is connected to the PIC17CXX. For Rext values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high Rext values (e.g. 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep Rext between 3 kΩ and 100 kΩ.

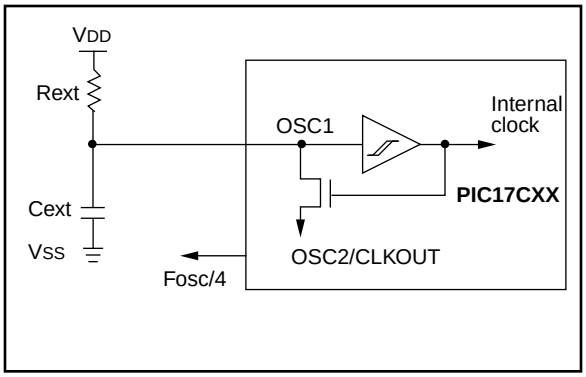
Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With little or no external capacitance, oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 18.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 18.0 for variation of oscillator frequency due to VDD for given Rext/Cext values as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic (see Figure 3-2 for waveform).

FIGURE 14-7: RC OSCILLATOR MODE



ADDWFC **ADD WREG and Carry bit to f**

Syntax: [*label*] ADDWFC f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (WREG) + (f) + C → (dest)

Status Affected: OV, C, DC, Z

Encoding:

0001	000d	ffff	ffff

Description: Add WREG, the Carry Flag and data memory location 'f'. If 'd' is 0, the result is placed in WREG. If 'd' is 1, the result is placed in data memory location 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: `ADDWFC REG 0`

Before Instruction
Carry bit = 1
REG = 0x02
WREG = 0x4D

After Instruction
Carry bit = 0
REG = 0x02
WREG = 0x50

ANDLW **And Literal with WREG**

Syntax: [*label*] ANDLW k

Operands: $0 \le k \le 255$

Operation: (WREG) .AND. (k) → (WREG)

Status Affected: Z

Encoding:

1011	0101	kkkk	kkkk

Description: The contents of WREG are AND'ed with the 8-bit literal 'k'. The result is placed in WREG.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Execute	Write to WREG

Example: `ANDLW 0x5F`

Before Instruction
WREG = 0xA3

After Instruction
WREG = 0x03

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT
0 → WDT postscaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

0000	0000	0000	0100

Description: CLRWDT instruction resets the watchdog timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ALUSTA	Execute	NOP

Example: CLRWDT

Before Instruction
WDT counter = ?

After Instruction
WDT counter = 0x00
WDT Postscaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

COMF **Complement f**

Syntax: [*label*] COMF f,d

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]

Operation: $(\bar{f})$ → (dest)

Status Affected: Z

Encoding:

0001	001d	ffff	ffff

Description: The contents of register 'f' are complemented. If 'd' is 0 the result is stored in WREG. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register 'f'

Example: COMF REG1,0

Before Instruction
REG1 = 0x13

After Instruction
REG1 = 0x13
WREG = 0xEC

MOVFP **Move f to p**

Syntax: [*label*] MOVFP f,p

Operands: $0 \le f \le 255$
$0 \le p \le 31$

Operation: (f) → (p)

Status Affected: None

Encoding:

011p	pppp	ffff	ffff

Description: Move data from data memory location 'f' to data memory location 'p'. Location 'f' can be anywhere in the 256 word data space (00h to FFh) while 'p' can be 00h to 1Fh.

Either 'p' or 'f' can be WREG (a useful special situation).

MOVFP is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port). Both 'f' and 'p' can be indirectly addressed.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register 'p'

Example: MOVFP REG1, REG2

Before Instruction
REG1 = 0x33,
REG2 = 0x11

After Instruction
REG1 = 0x33,
REG2 = 0x33

MOVLB **Move Literal to low nibble in BSR**

Syntax: [*label*] MOVLB k

Operands: $0 \le k \le 15$

Operation: k → (BSR<3:0>)

Status Affected: None

Encoding:

1011	1000	uuuu	kkkk

Description: The four bit literal 'k' is loaded in the Bank Select Register (BSR). Only the low 4-bits of the Bank Select Register are affected. The upper half of the BSR is unchanged. The assembler will encode the “u” fields as '0'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'u:k'	Execute	Write literal 'k' to BSR<3:0>

Example: MOVLB 0x5

Before Instruction
BSR register = 0x22

After Instruction
BSR register = 0x25

Note: For the PIC17C42, only the low four bits of the BSR register are physically implemented. The upper nibble is read as '0'.

Applicable Devices	42	R42	42A	43	R43	44

17.2 DC CHARACTERISTICS: PIC17C42-16 (Commercial, Industrial) PIC17C42-25 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in Section 17.1				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Input Low Voltage					
	VIL	I/O ports					
D030		with TTL buffer	VSS	–	0.8	V	
D031		with Schmitt Trigger buffer	VSS	–	0.2VDD	V	
D032		$\overline{MCLR}$, OSC1 (in EC and RC mode)	Vss	–	0.2VDD	V	Note1
D033		OSC1 (in XT, and LF mode)	–	0.5VDD	–	V	
		Input High Voltage					
	VIH	I/O ports		–			
D040		with TTL buffer	2.0	–	VDD	V	
D041		with Schmitt Trigger buffer	0.8VDD	–	VDD	V	
D042		$\overline{MCLR}$	0.8VDD	–	VDD	V	Note1
D043		OSC1 (XT, and LF mode)	–	0.5VDD	–	V	
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15VDD*	–	–	V	
		Input Leakage Current (Notes 2, 3)					
D060	IIL	I/O ports (except RA2, RA3)	–	–	±1	µA	Vss ≤ VPIN ≤ VDD, I/O Pin at hi-impedance PORTB weak pull-ups disabled
D061		$\overline{MCLR}$	–	–	±2	µA	VPIN = Vss or VPIN = VDD
D062		RA2, RA3			±2	µA	Vss ≤ VRA2, VRA3 ≤ 12V
D063		OSC1, TEST	–	–	±1	µA	Vss ≤ VPIN ≤ VDD
D064		$\overline{MCLR}$	–	–	10	µA	VMCLR = VPP = 12V (when not programming)
D070	IPURB	PORTB weak pull-up current	60	200	400	µA	VPIN = VSS, $\overline{RBPU}$ = 0

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

†† Design guidance to attain the AC timing specifications. These loads are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

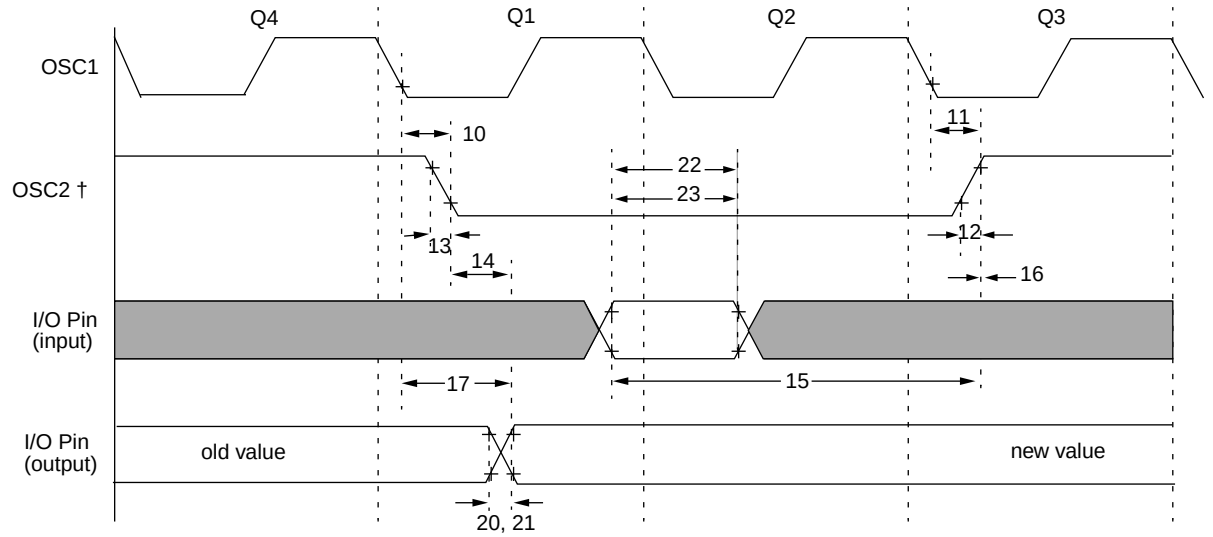
4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The $\overline{MCLR}$/Vpp pin may be kept in this range at times other than programming, but this is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 17-3: CLKOUT AND I/O TIMING



† In EC and RC modes only.

TABLE 17-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓	—	15 ‡	30 ‡	ns	Note 1
11	TosH2ckH	OSC1↑ to CLKOUT↑	—	15 ‡	30 ‡	ns	Note 1
12	TckR	CLKOUT rise time	—	5 ‡	15 ‡	ns	Note 1
13	TckF	CLKOUT fall time	—	5 ‡	15 ‡	ns	Note 1
14	TckH2ioV	CLKOUT↑ to Port out valid	—	—	0.5TCY + 20‡	ns	Note 1
15	TioV2ckH	Port in valid before CLKOUT↑	0.25TCY + 25 ‡	—	—	ns	Note 1
16	TckH2ioI	Port in hold after CLKOUT↑	0 ‡	—	—	ns	Note 1
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	—	100 ‡	ns	
20	TioR	Port output rise time	—	10 ‡	35 ‡	ns	
21	TioF	Port output fall time	—	10 ‡	35 ‡	ns	
22	TinHL	INT pin high or low time	25 *	—	—	ns	
23	TrbHL	RB7:RB0 change INT high or low time	25 *	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Measurements are taken in EC Mode where OSC2 output = 4 x TOSC = TCY.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 17-7: CAPTURE TIMINGS

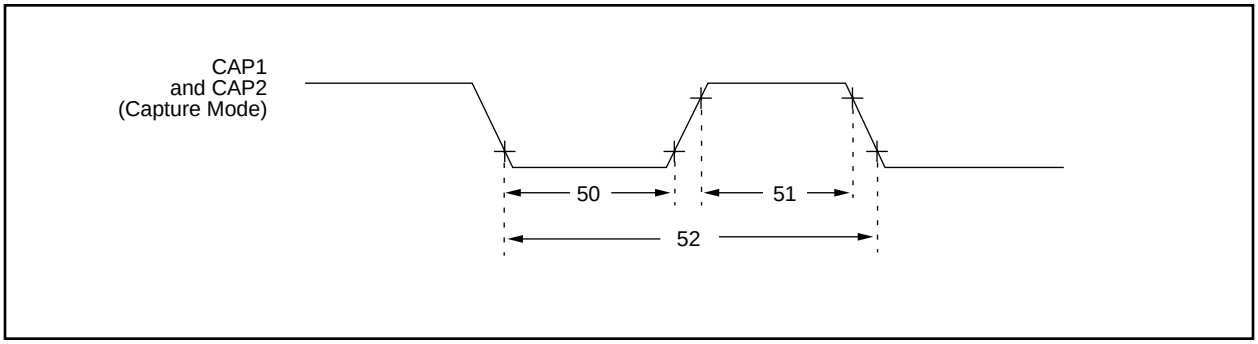


TABLE 17-7: CAPTURE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
50	TccL	Capture1 and Capture2 input low time	10 *	—	—	ns	
51	TccH	Capture1 and Capture2 input high time	10 *	—	—	ns	
52	TccP	Capture1 and Capture2 input period	$\frac{2\ T_{CY}}{N}$ §	—	—	ns	N = prescale value (4 or 16)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

FIGURE 17-8: PWM TIMINGS

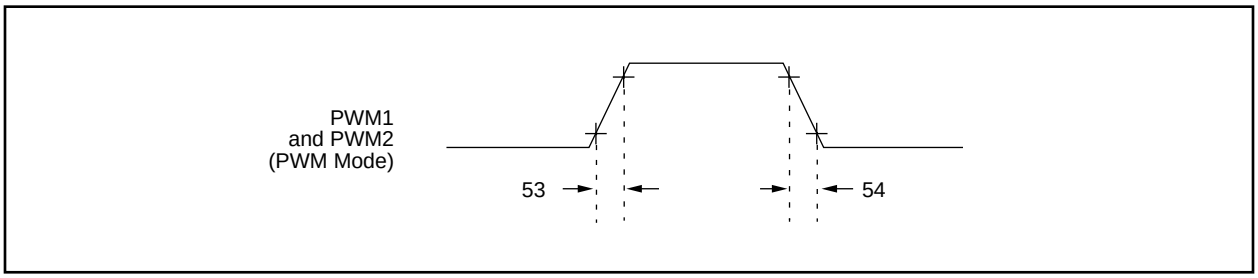


TABLE 17-8: PWM REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
53	TccR	PWM1 and PWM2 output rise time	—	10 *	35 *§	ns	
54	TccF	PWM1 and PWM2 output fall time	—	10 *	35 *§	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Applicable Devices	42	R42	42A	43	R43	44

19.2 DC CHARACTERISTICS: PIC17LC42A/43/LC44 (Commercial, Industrial) PIC17LCR42/43 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	2.5	–	6.0	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.060 *	–	–	mV/ms	See section on Power-on Reset for details
D010	IDD	Supply Current (Note 2)	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011			–	6	12 *	mA	FOSC = 8 MHz
D014			–	95	150	µA	FOSC = 32 kHz, WDT disabled (EC osc configuration)
D020	IPD	Power-down Current (Note 3)	–	10	40	µA	VDD = 5.5V, WDT enabled
D021			–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

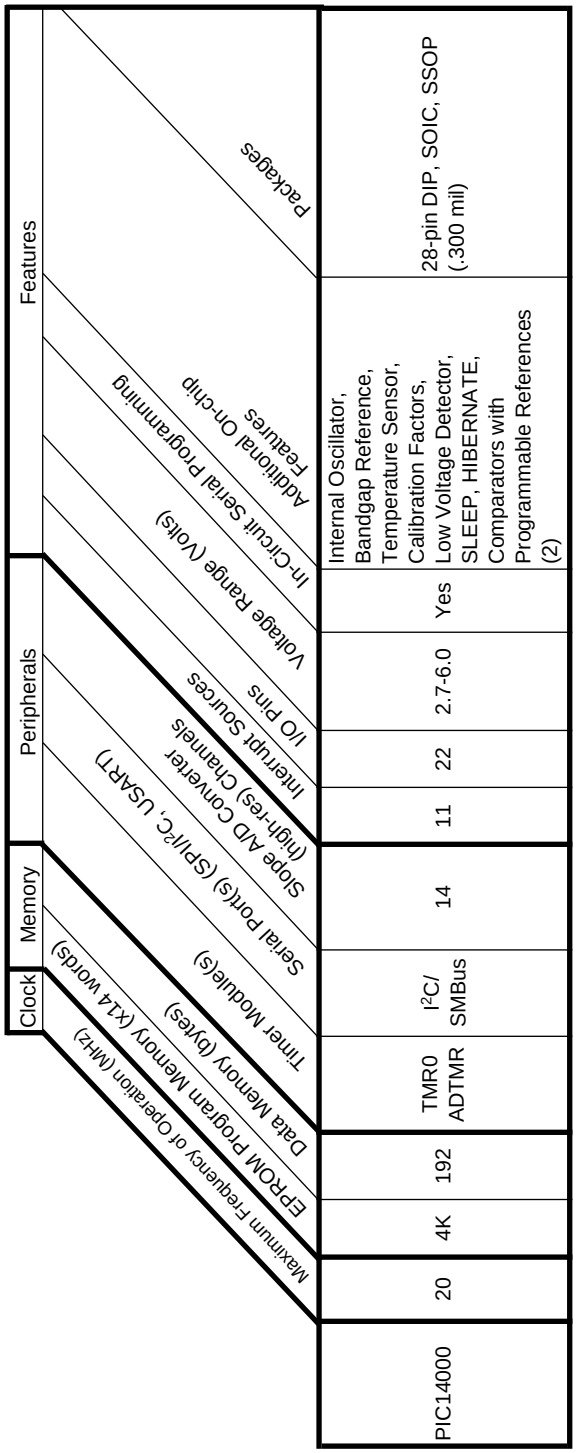
2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1=external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads needs to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, the current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

APPENDIX E: PIC16/17 MICROCONTROLLERS

E.1 PIC14000 Devices



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2. Dial your local CompuServe access number.
3. Depress the <Enter> key and a garbage string will appear because CompuServe is expecting a 7E1 setting.
4. Type +, depress the <Enter> key and “Host Name:” will appear.
5. Type MCHIPBBS, depress the <Enter> key and you will be connected to the Microchip BBS.

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